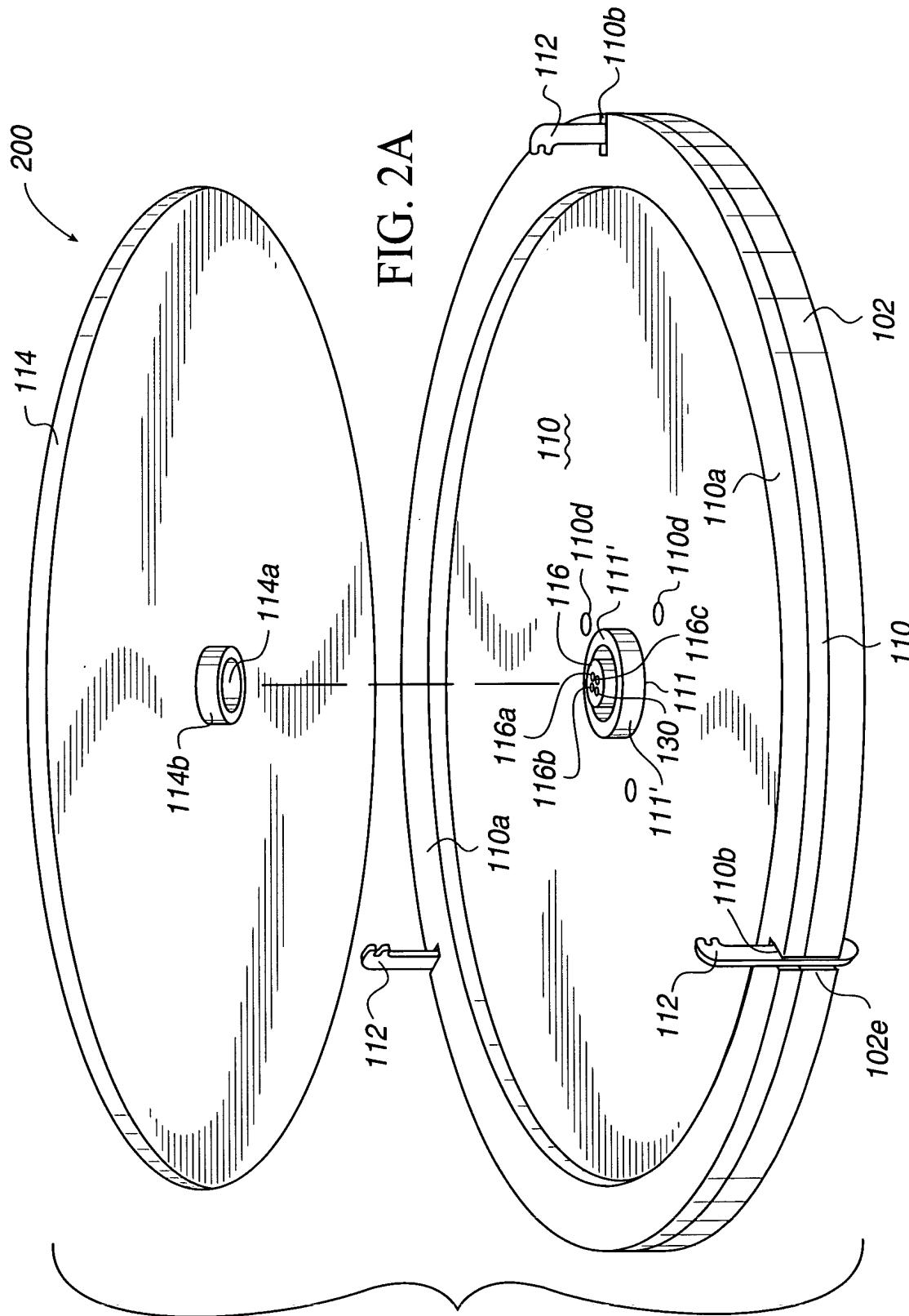




Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME
Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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FIG. 2A





Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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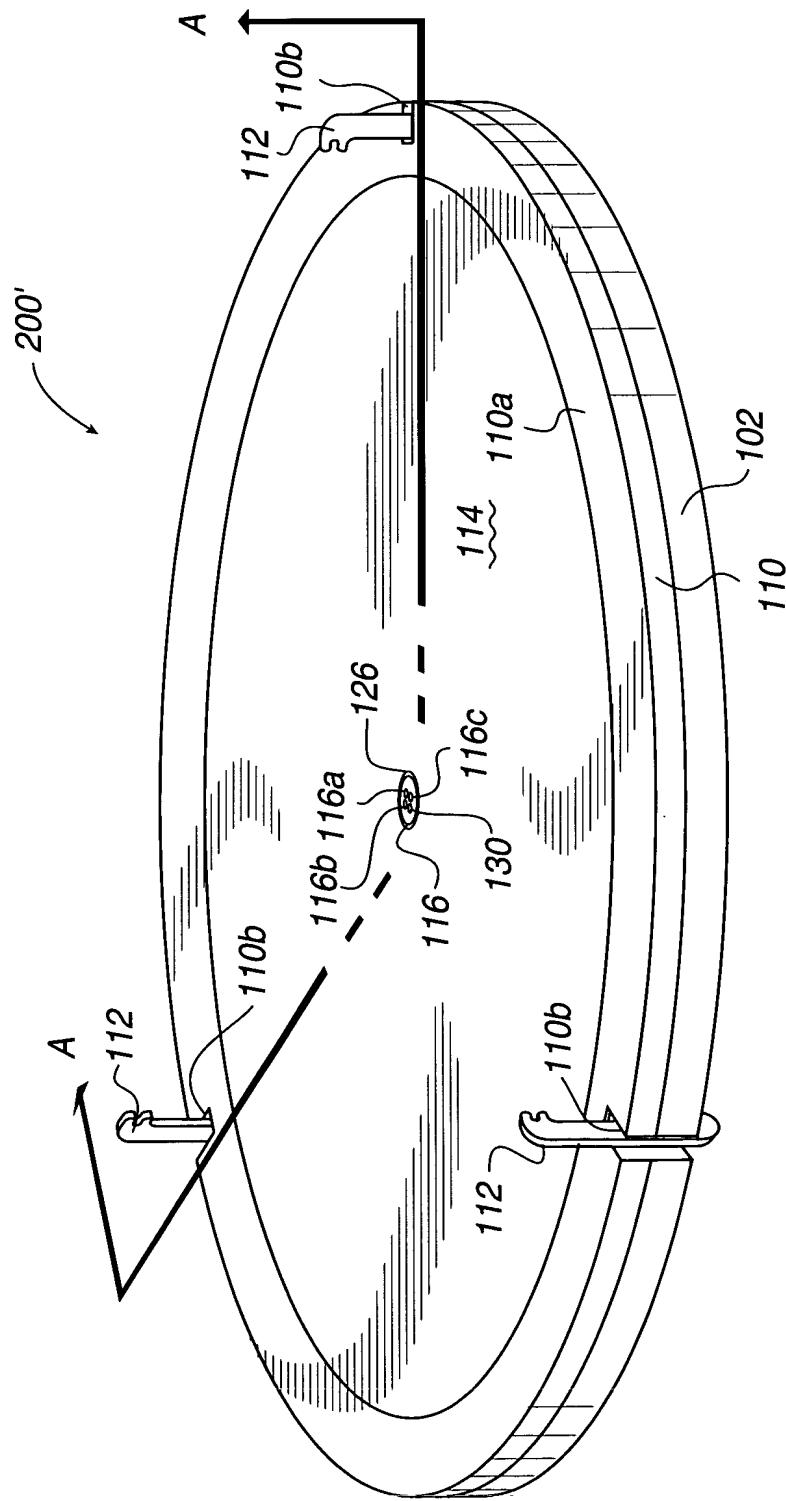
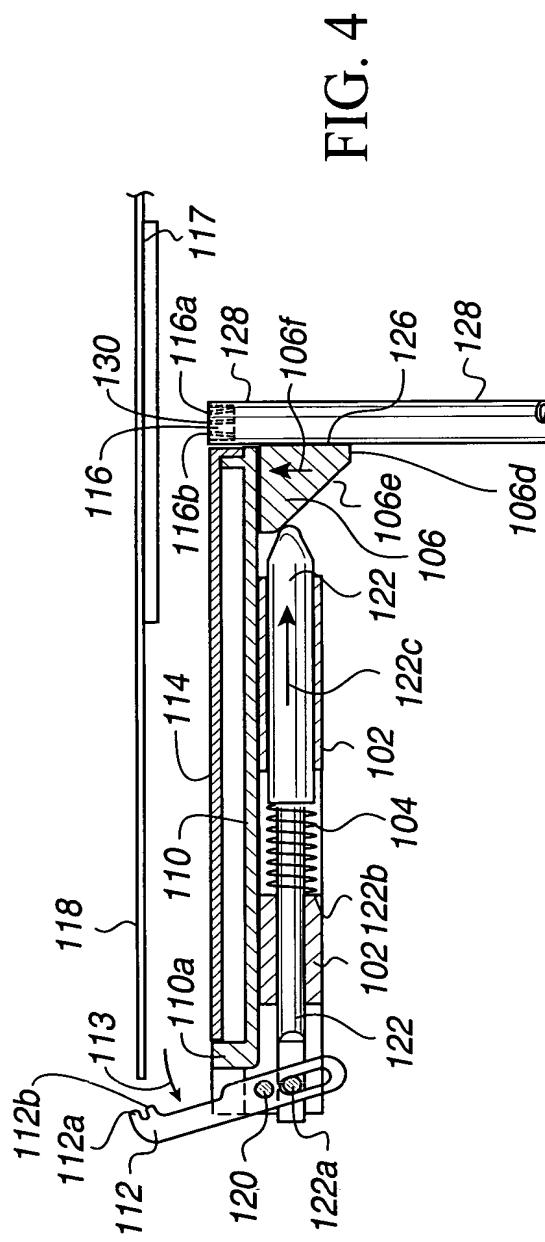
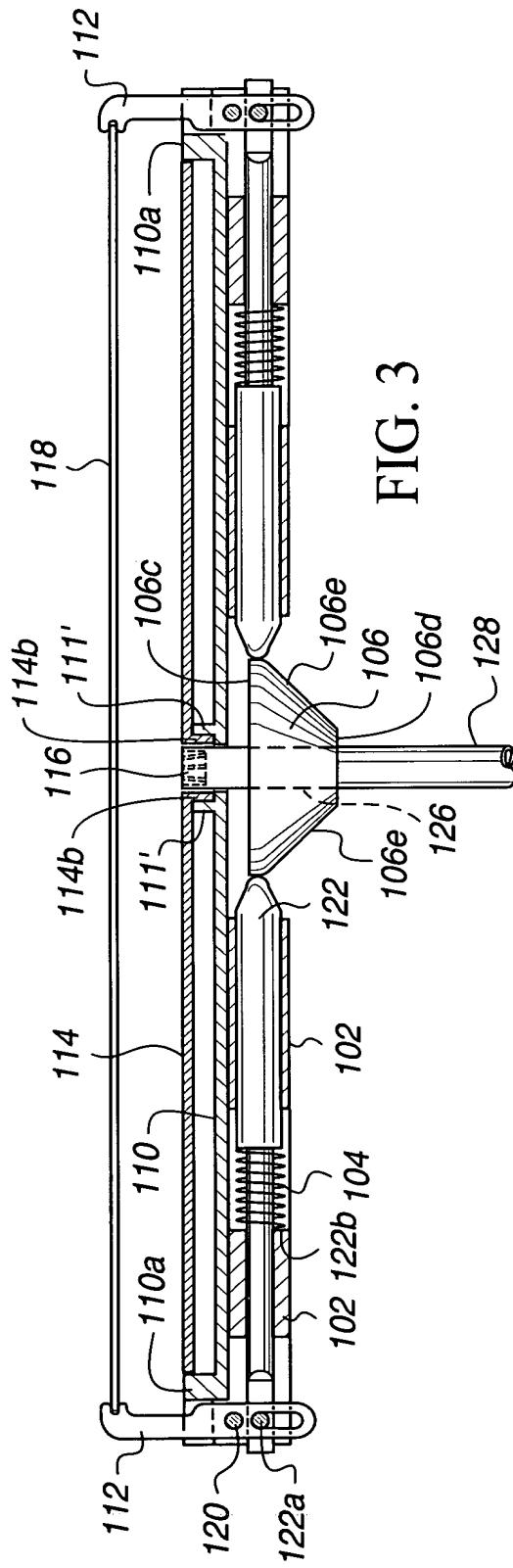


FIG. 2B



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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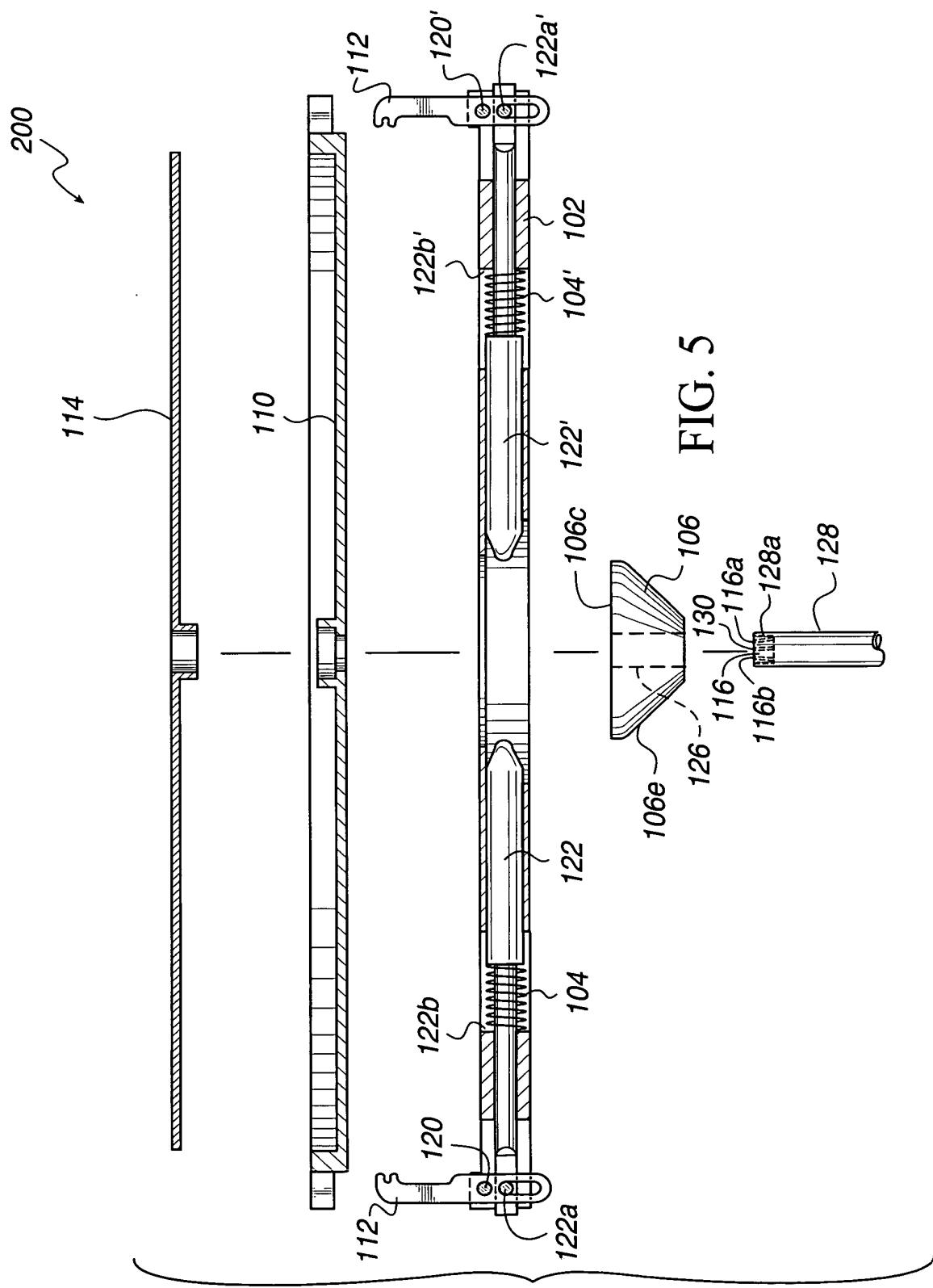
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Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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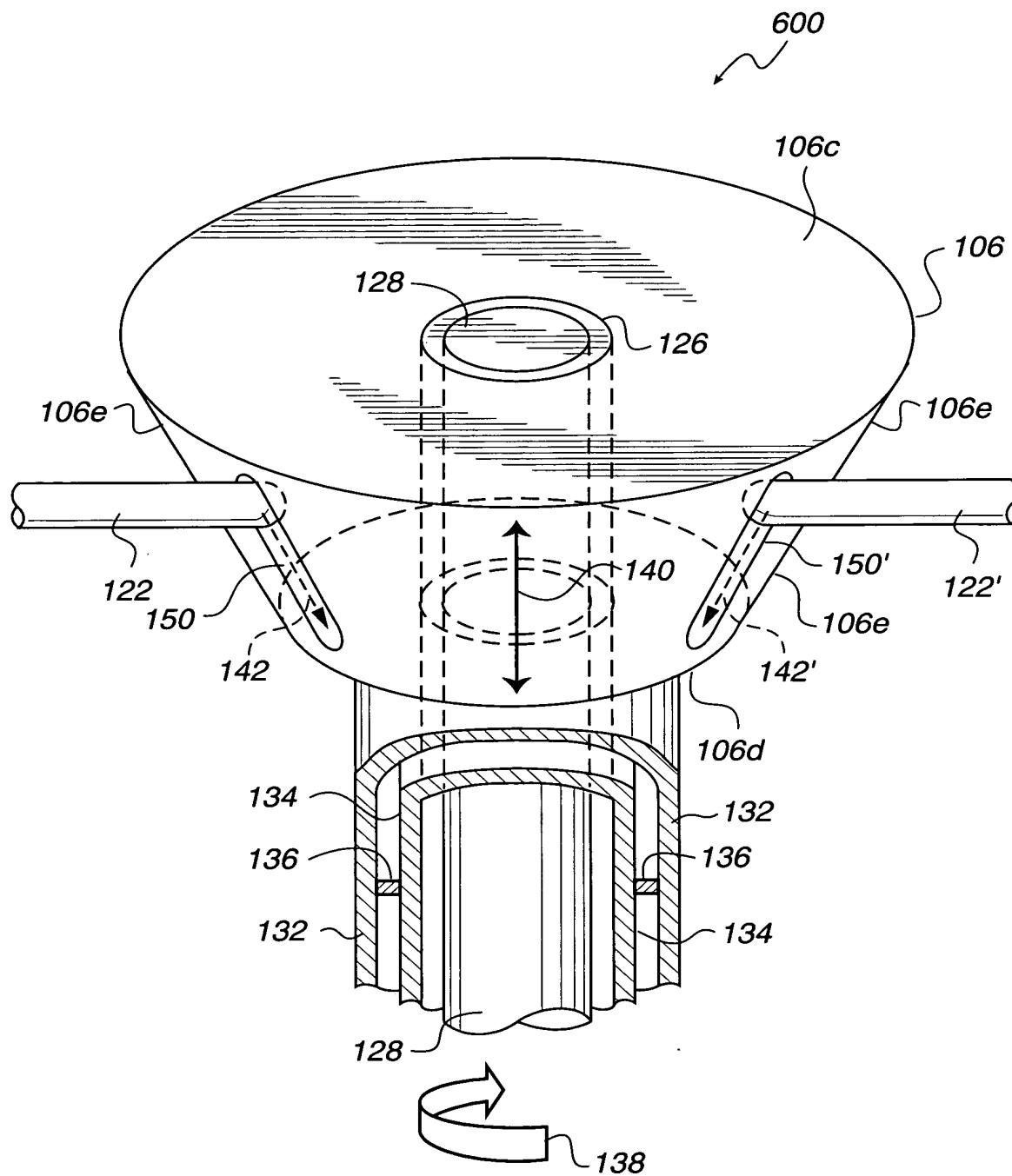


FIG. 6A



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME
Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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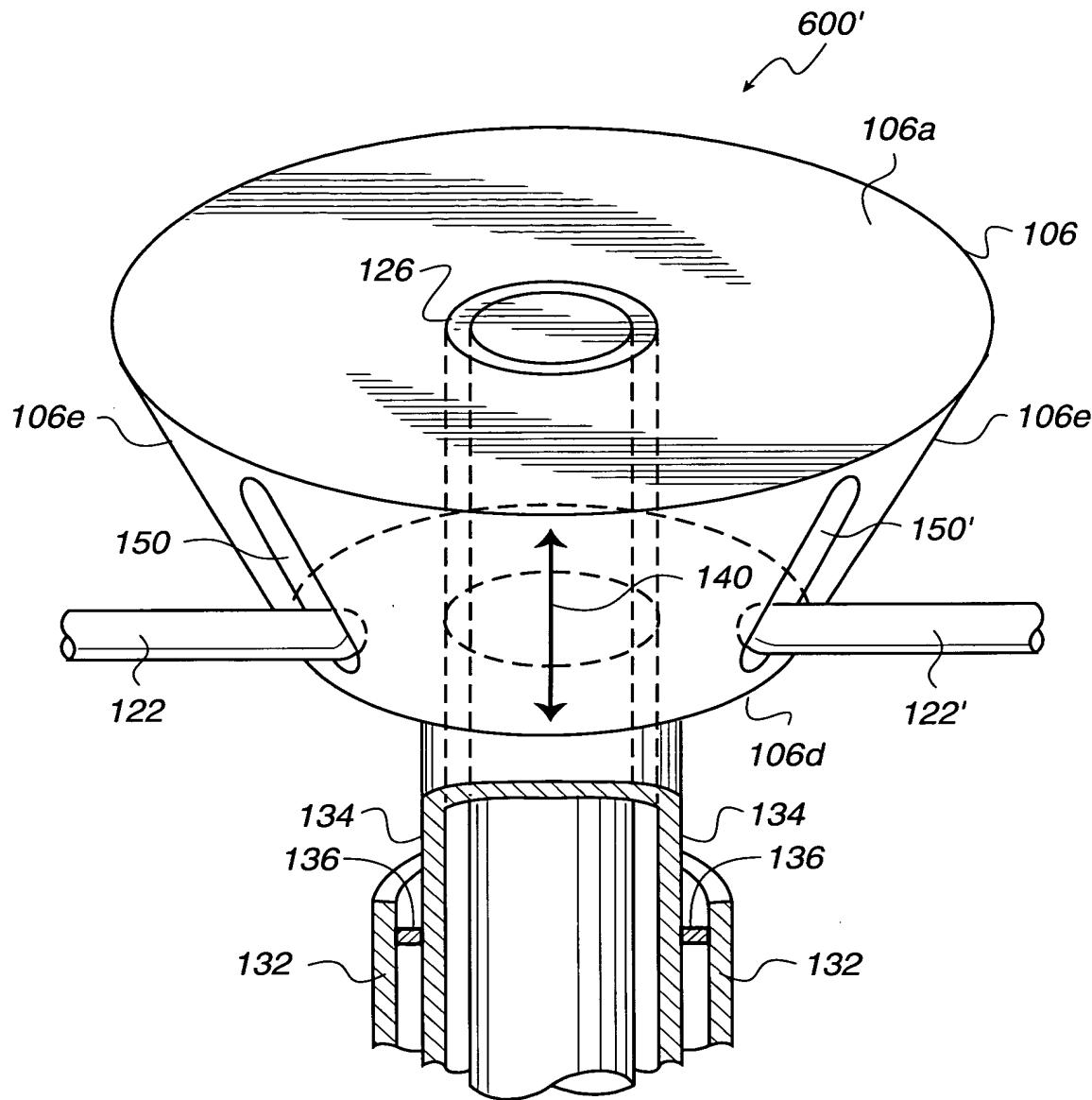


FIG. 6B



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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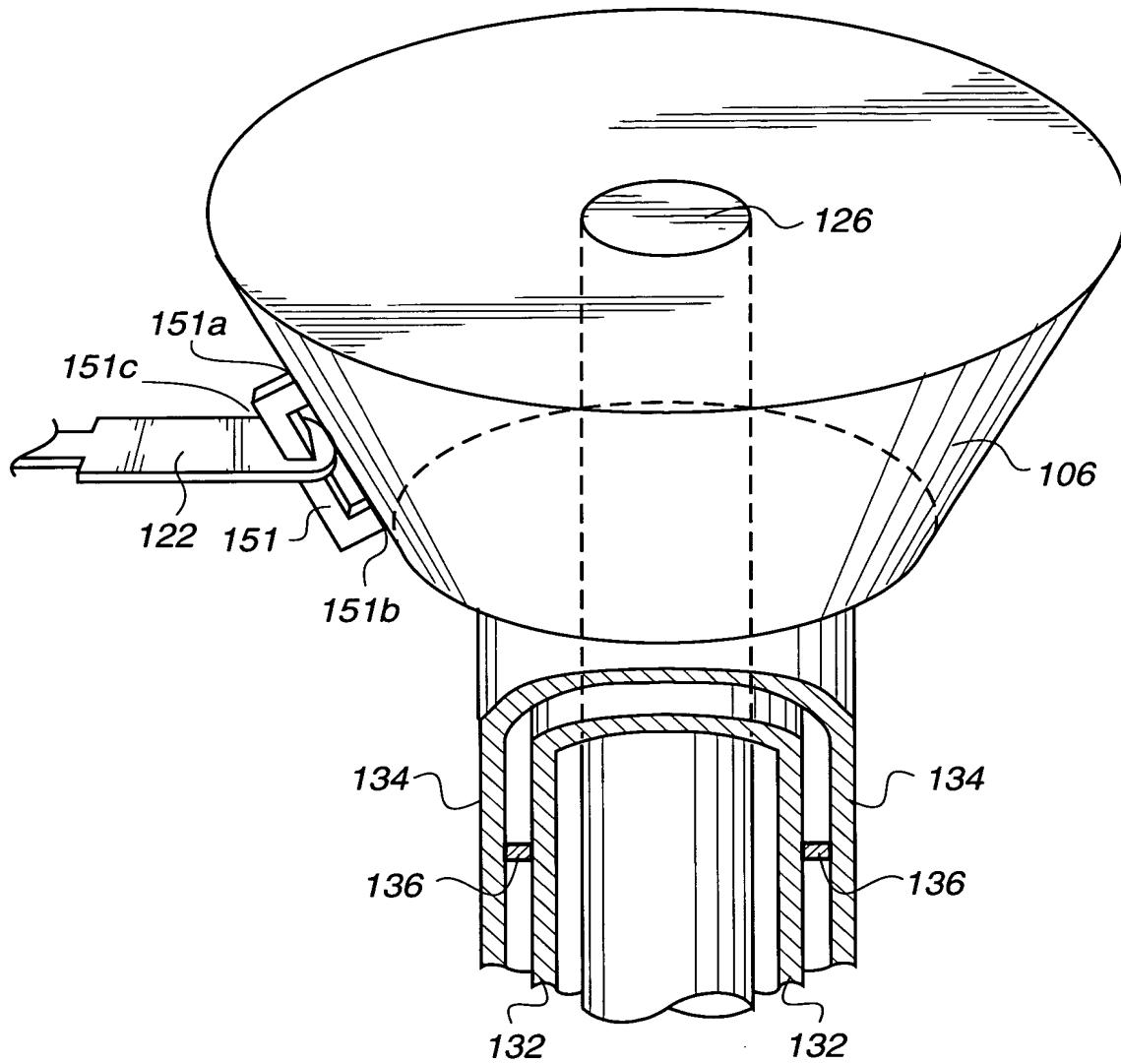


FIG. 6C



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME
Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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FIG. 7A

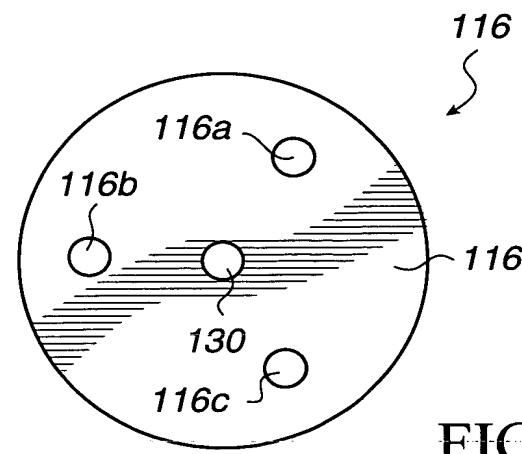
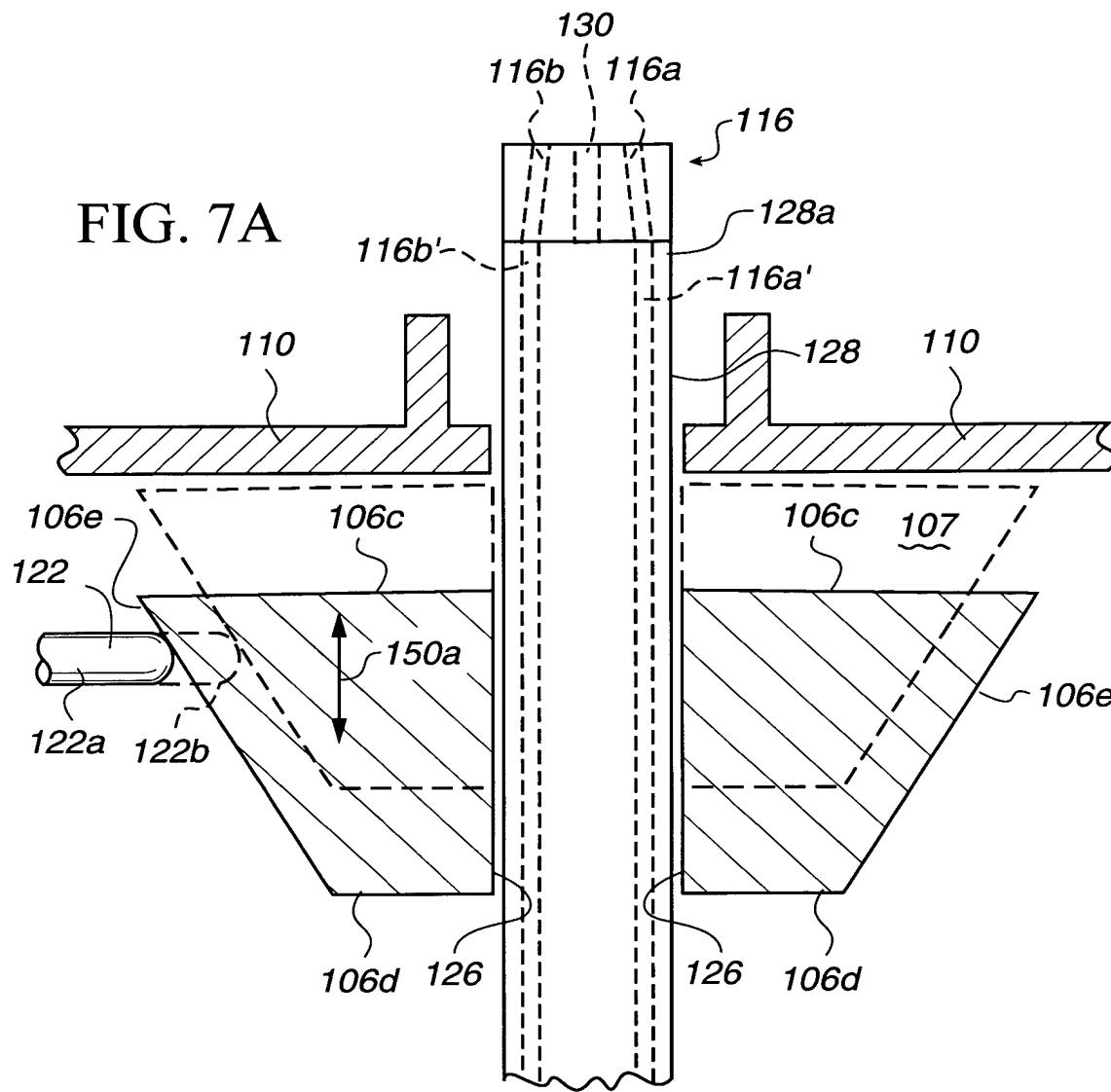


FIG. 7B



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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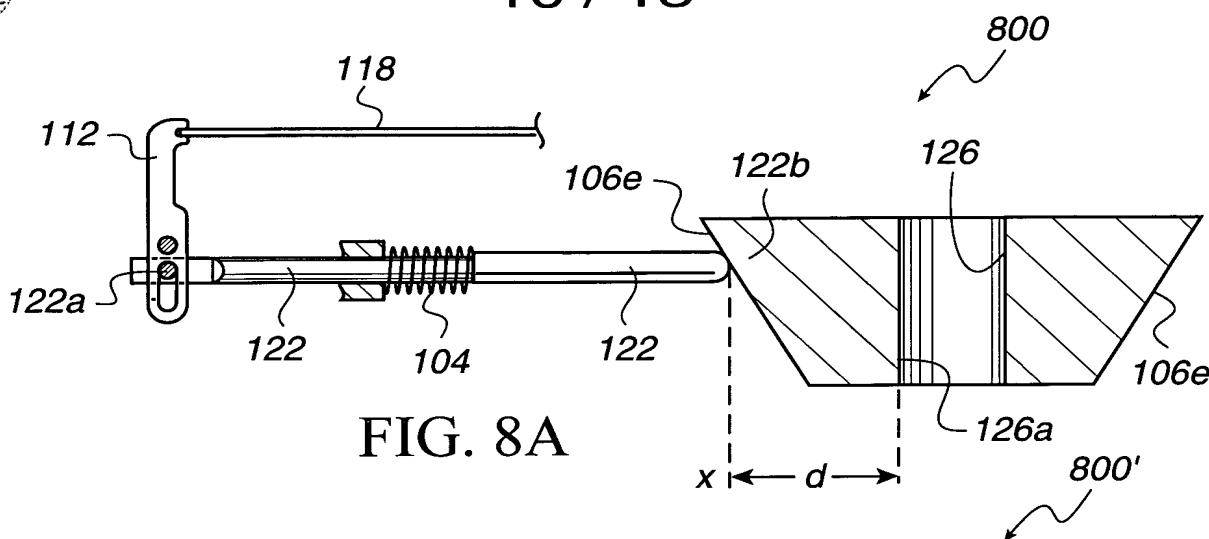


FIG. 8A

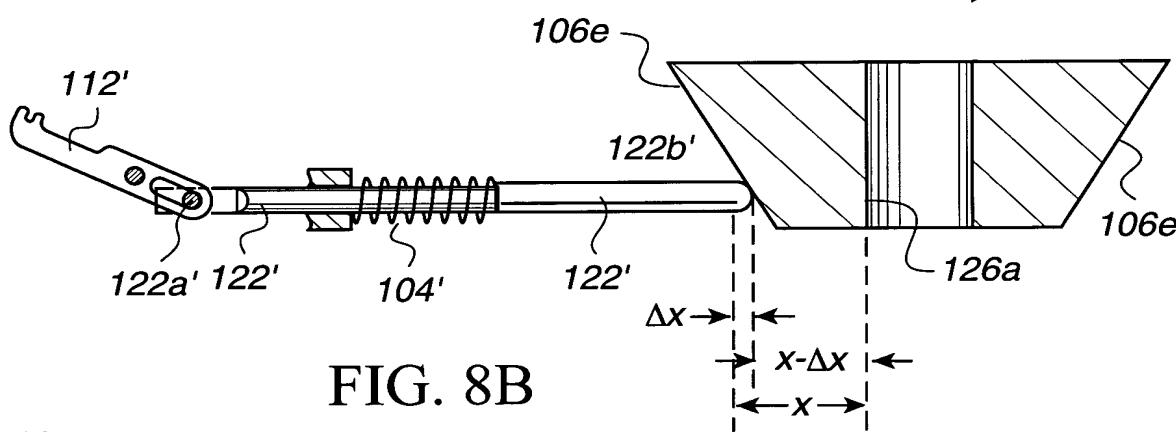


FIG. 8B

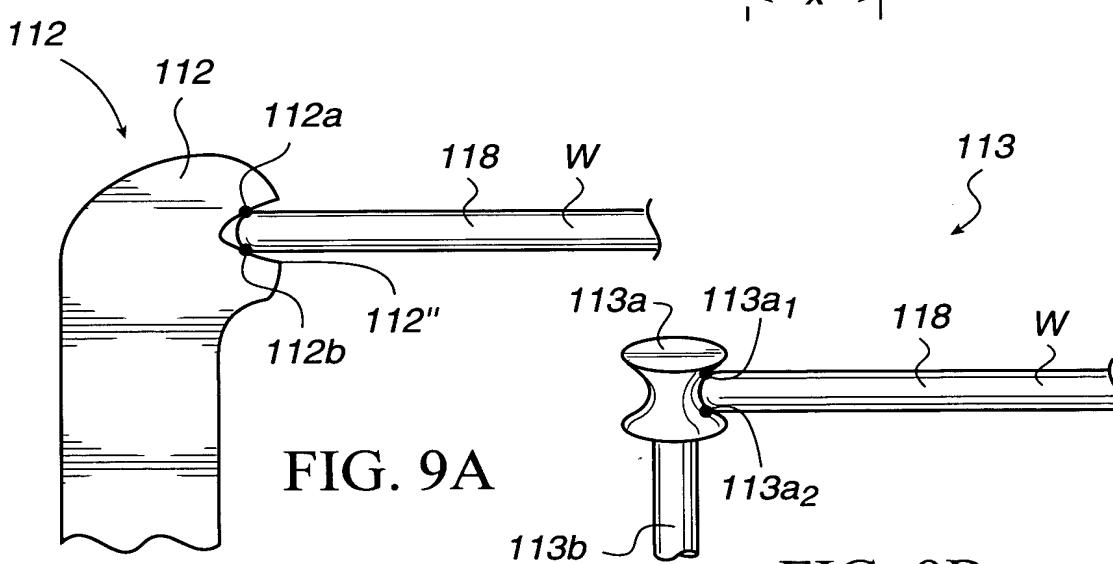


FIG. 9A

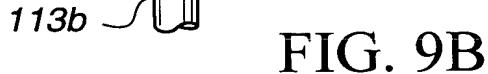


FIG. 9B



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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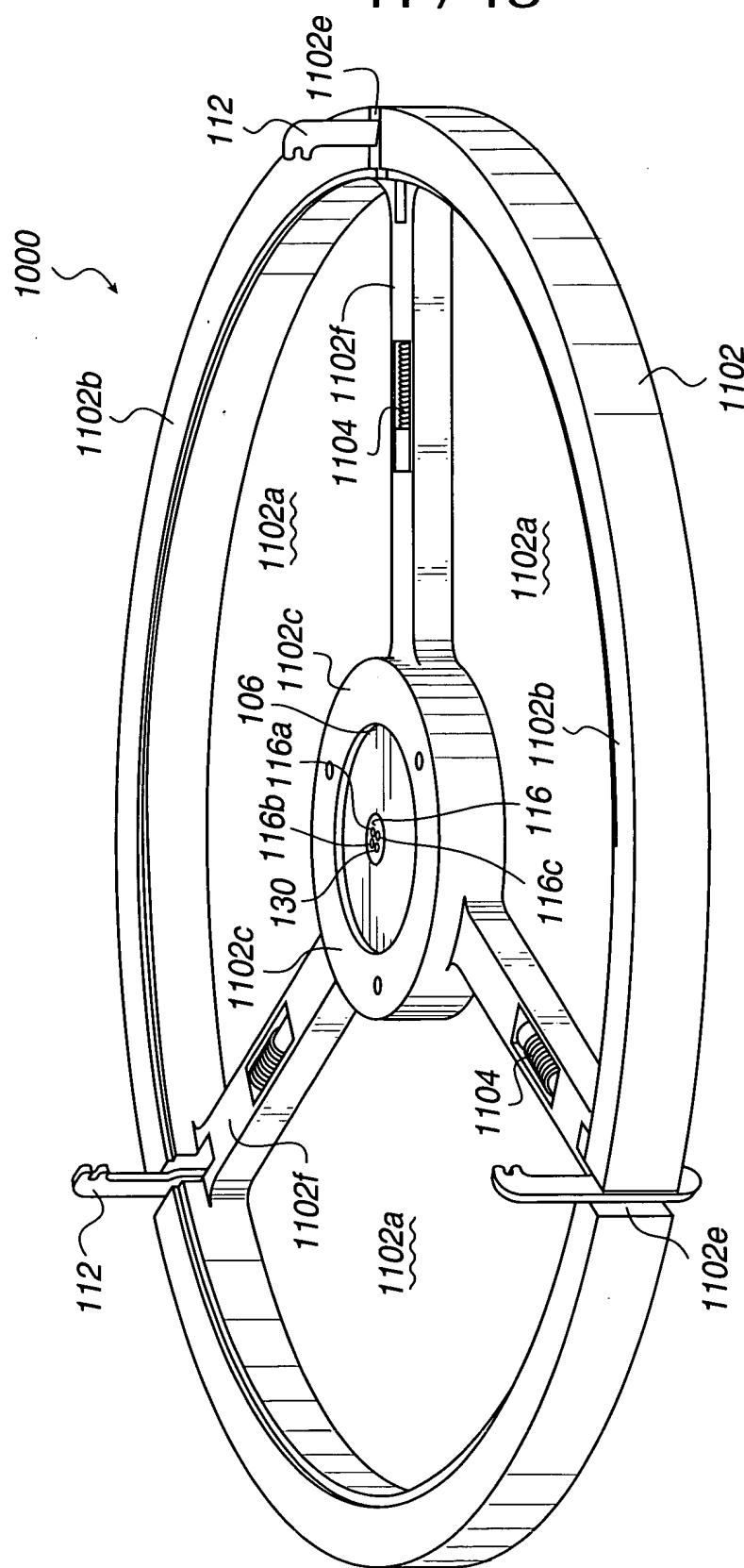


FIG. 10



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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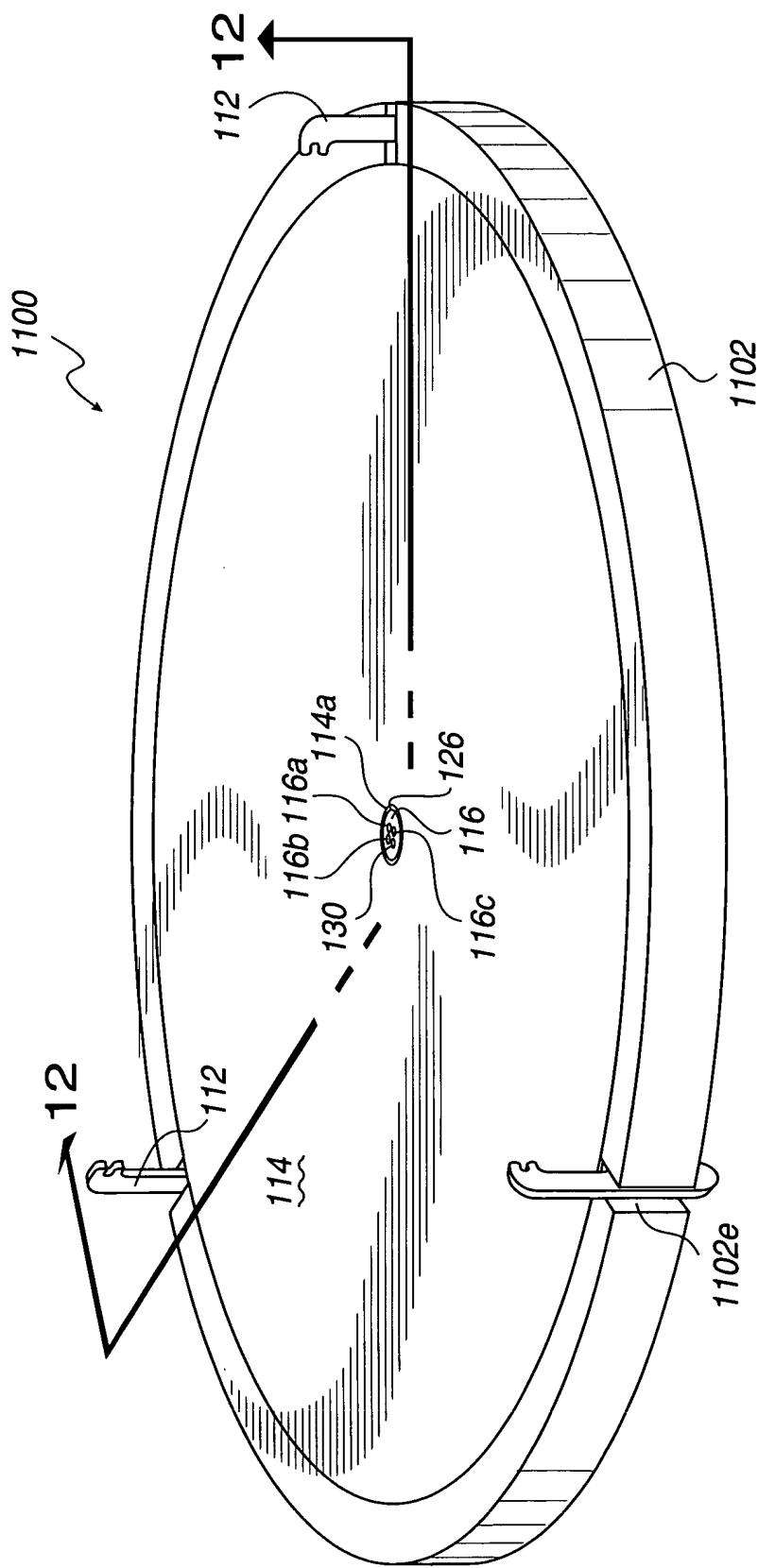
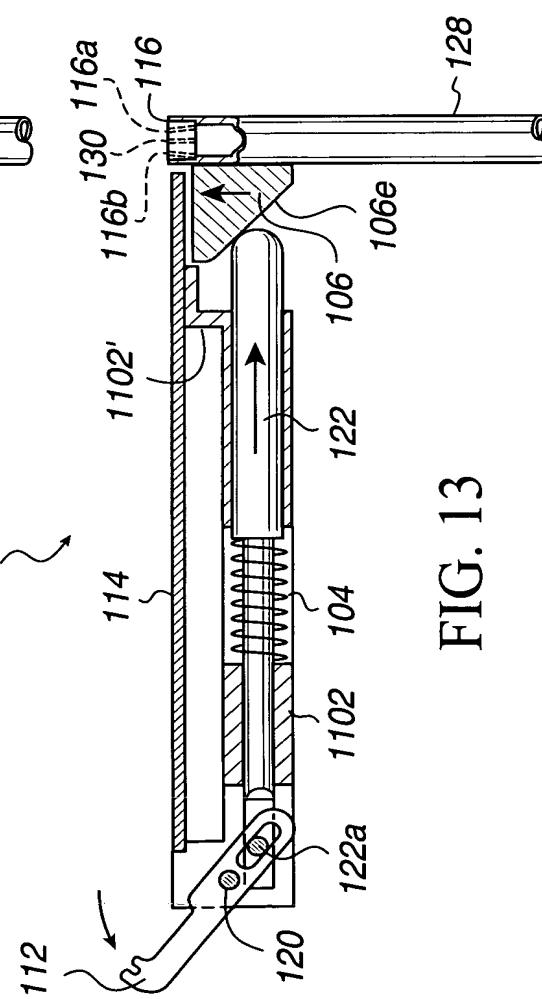
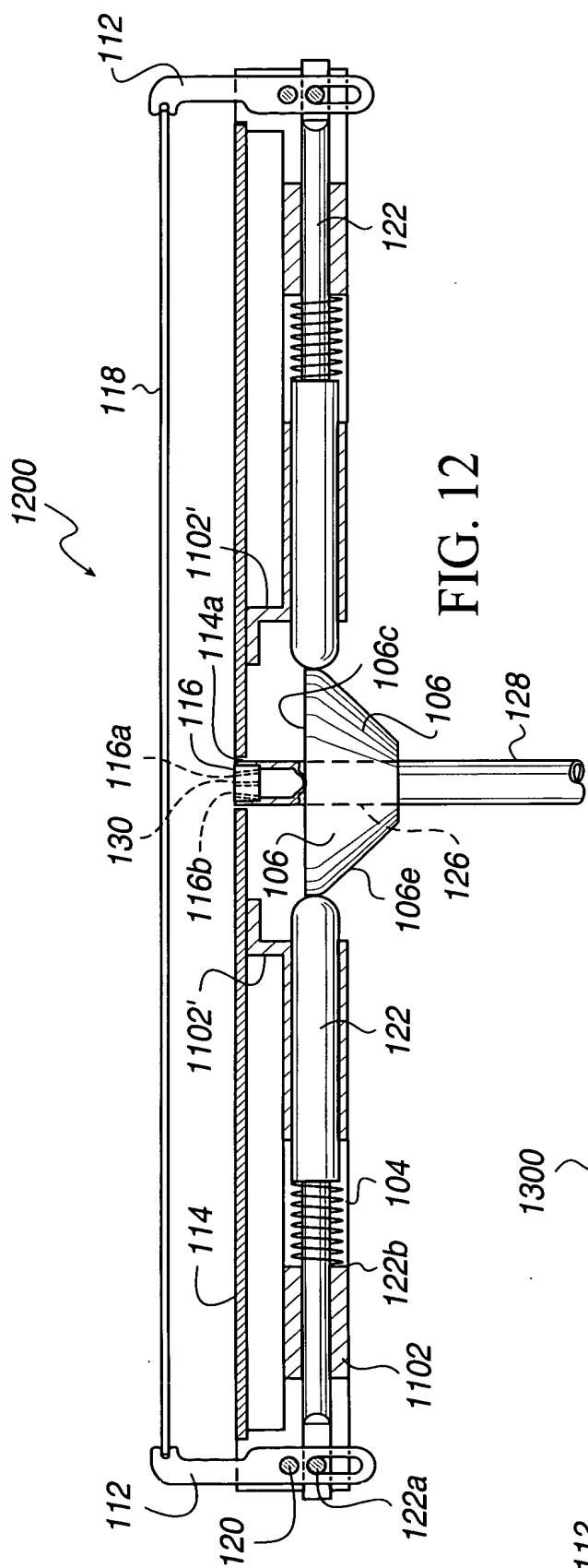


FIG. 11



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME
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Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY
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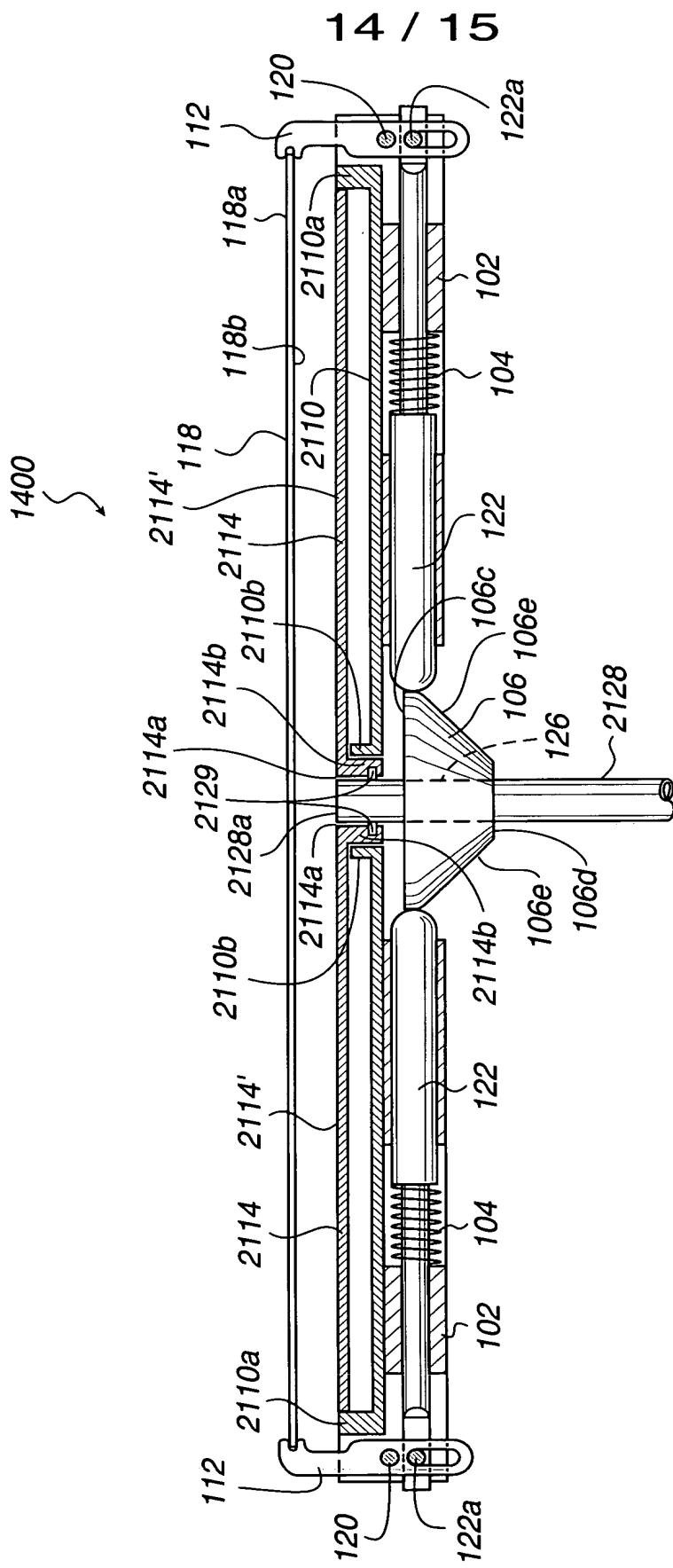


FIG. 14



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME
Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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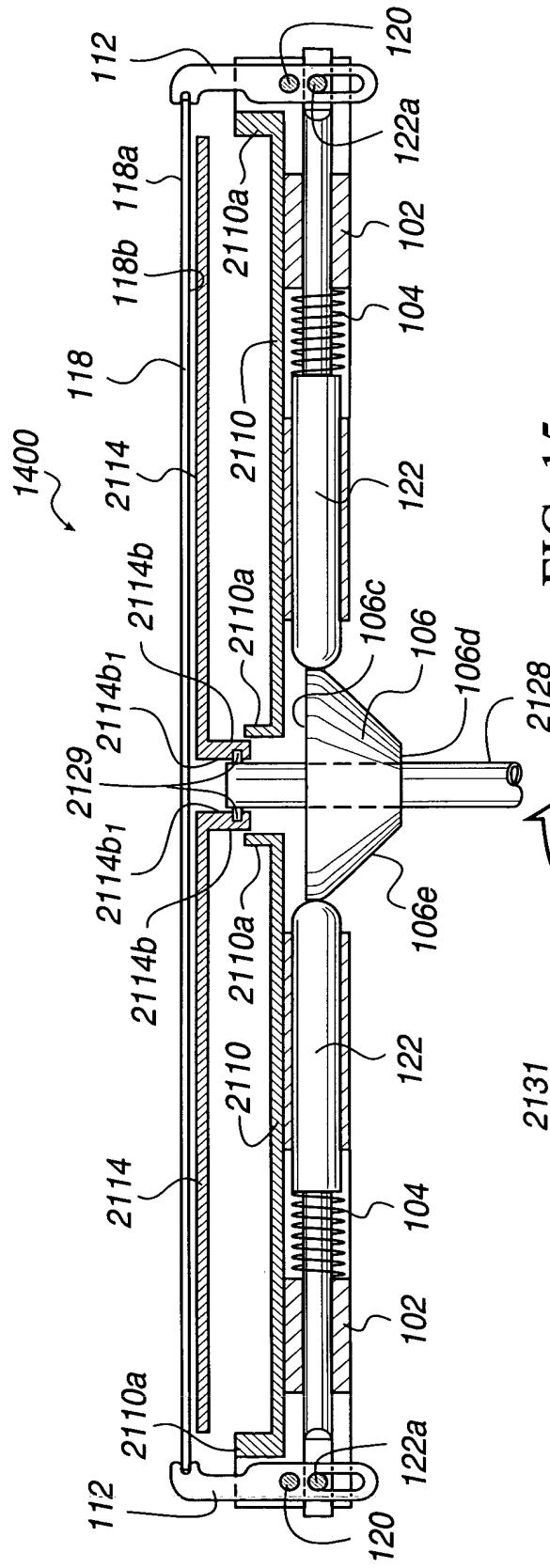


FIG. 15

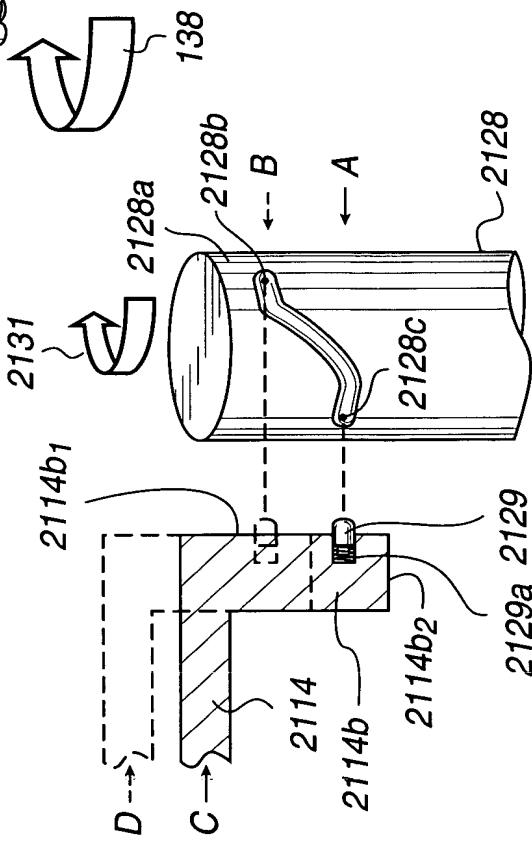


FIG. 16